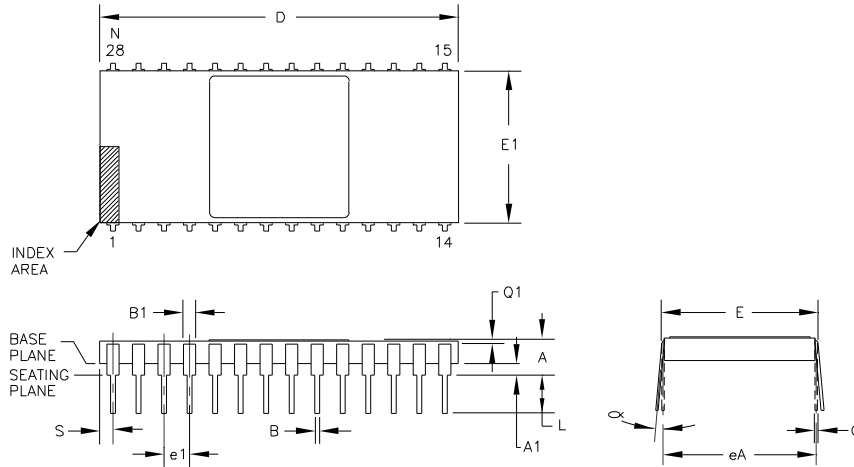


Package Number 149 - 28-Lead Side Braze DIP, .600 Wide



DIM	INCHES		MILLIMETERS		N	Q	E	DIM	INCHES		MILLIMETERS		N	Q	E
	MIN.	MAX.	MIN.	MAX.					MIN.	MAX.	MIN.	MAX.			
A	.085	.190	2.16	4.83				α	0°	15°	0°	15°	3		
A1	.020	.070	0.51	1.78											
B	.015	.023	0.38	0.58	5										
B1	.038	.060	0.97	1.52	5										
C	.008	.012	0.20	0.30											
D	1.380	1.430	35.05	36.32											
E	.595	.625	15.11	15.88											
E1	.580	.610	14.73	15.49	6										
e1	.100	TYP.	2.54	TYP.	2										
eA	.600	TYP.	15.24	TYP.	2										
L	.125	.175	3.18	4.45											
N	28		28		4										
Q1	.010	--	0.25	--											
S	.030	.065	0.76	1.65											

- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5-1973.
 2. LEADS WITHIN .005 IN. (0.13mm) RADIUS OF TRUE POSITION (TP) AT GAUGE PLANE WITH MAXIMUM MATERIAL CONDITION AND UNIT INSTALLED.
 3. α APPLIES TO SPREAD LEADS PRIOR TO INSTALLATION.
 4. N IS THE NUMBER OF TERMINAL POSITIONS.

5. OUTLINES ON WHICH THE SEATING PLANE IS COINCIDENT WITH THE PLANE (A1 = 0), TERMINALS LEAD STANDOFFS ARE NOT REQUIRED, AND B1 MAY EQUAL B ALONG ANY PART OF THE LEAD ABOVE THE SEATING/BASE PLANE.
6. E1 DOES NOT INCLUDE PARTICLES OF PACKING MATERIALS.
7. CONTROLLING DIMENSION: INCH.
8. A VISUAL INDEX FEATURE MUST BE LOCATED WITHIN THE CROSS-HATCHED AREA.

PACKAGE NUMBER: ZZ149 REV.: C
JEDEC NUMBER: MO-038-AB



PACKAGE DRAWING

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